

SL3S1206

UCODE 9

Rev. 3.0 — 15 December 2020
530930

Product data sheet
COMPANY PROPRIETARY

1 General description

The UCODE 9 is the latest NXP products of the UCODE family. UCODE 9 offers high performance and features for use in the most demanding RFID tagging applications.

Particularly well suited for inventory management applications, for example, retail and fashion, baggage tagging, and smart logistics with its great RF performance for any given form factor, UCODE 9 enables long read range and fast an inventory of dense RFID tag populations. With its broadband design, it offers the possibility to manufacture true global RFID labels with great performance over worldwide regulations.



2 Features and benefits

2.1 Key features

- Read sensitivity -24 dBm
- Write sensitivity -22 dBm
- Innovative functionality
 - Drop-in replacement to UCODE 8 due to similar assembled input capacitance
 - Self-Adjust
 - Memory Safeguard
 - Dynamic backscatter
 - Pre-serialization of 96-bit EPC
- Compatible with single-slit antenna
- 96-bit unique tag identifier (TID) factory locked, including 48-bit unique serial number
- EPC Gen2v2.1

2.1.1 Memory

- 96-bit of EPC memory
- Supports pre-serialization of 96-bit EPC
- 96-bit Tag Identifier (TID) factory-locked
- 48-bit unique serial number factory-encoded into TID
- 32-bit kill password to permanently disable the tag
- Wide operating temperature range: -40 °C up to +85 °C
- Minimum 100k write cycle endurance

2.2 Supported features

- All mandatory commands of the EPCglobal Gen2v2.1 specification are implemented including:
 - Kill Command
- The following optional commands are implemented in conformance with the EPC specification:
 - BlockWrite (2 words, 32-bit)
- Self-Adjust for automated tag performance optimization

All supported features of the UCODE 9 can be activated using standard EPCglobal READ / WRITE / SELECT commands. No custom commands are needed to take advantage of all the features.

3 Applications

3.1 Target market

- Retail
 - Brick and mortar
 - E-commerce
 - Omnichannel
- Supply chain management
- Airline baggage tracking

3.2 Applications

- Highly accurate and fast inventory management, enabling omnichannel retail processes
- Tracking along the supply chain from source to store
- High-speed store checkout process, bringing convenience to the customer
- Loss prevention
- Brand protection
- After sales operations: return and warranty management

Apart from the applications mentioned above, please contact NXP Semiconductors for support.

4 Ordering information

Table 1. Ordering information

Type number	Package			
	Name	IC type	Description	Version
SL3S1206FUD2/HA	Wafer	UCODE 9	Die on sawn 12" 120 μm wafer 10 μm Polyimide spacer with Large Pads	Not applicable

5 Block diagram

The UCODE 9 IC consists of three major blocks:

- Analog interface
- Digital control
- EEPROM

The analog part provides stable supply voltage and demodulates data received from the reader which is then processed by the digital part. Further, the modulation transistor of the analog part transmits data back to the reader.

The digital section includes the state machines, processes the protocol, and handles communication with the EEPROM, which contains the EPC and the user data.

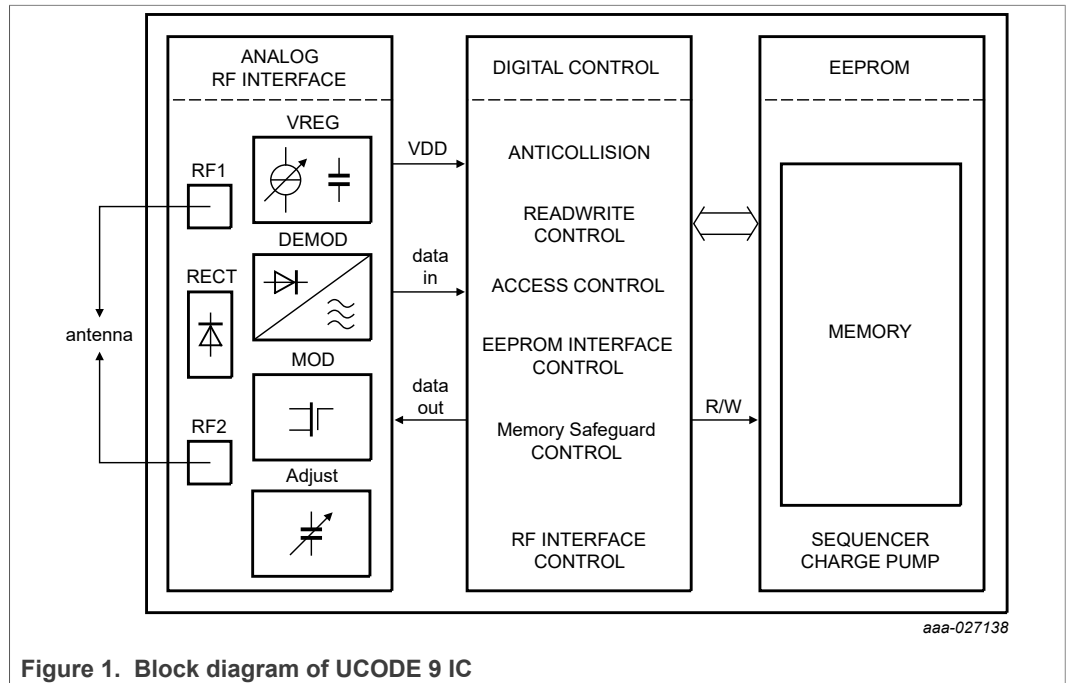
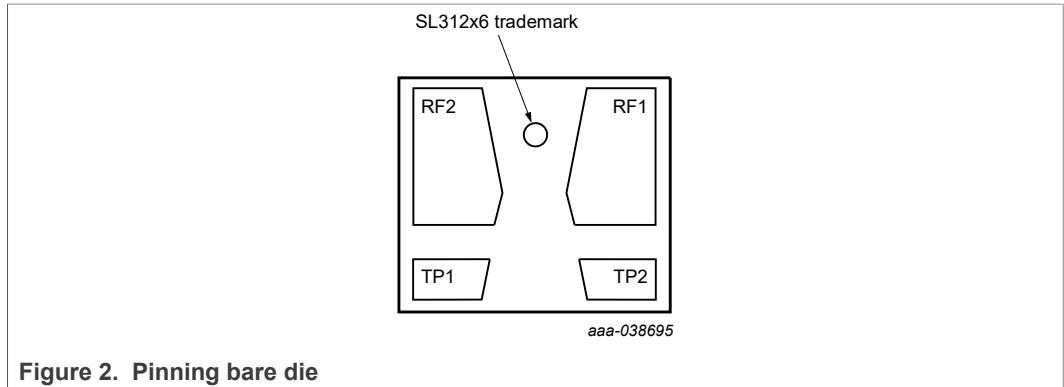


Figure 1. Block diagram of UCODE 9 IC

6 Pinning information

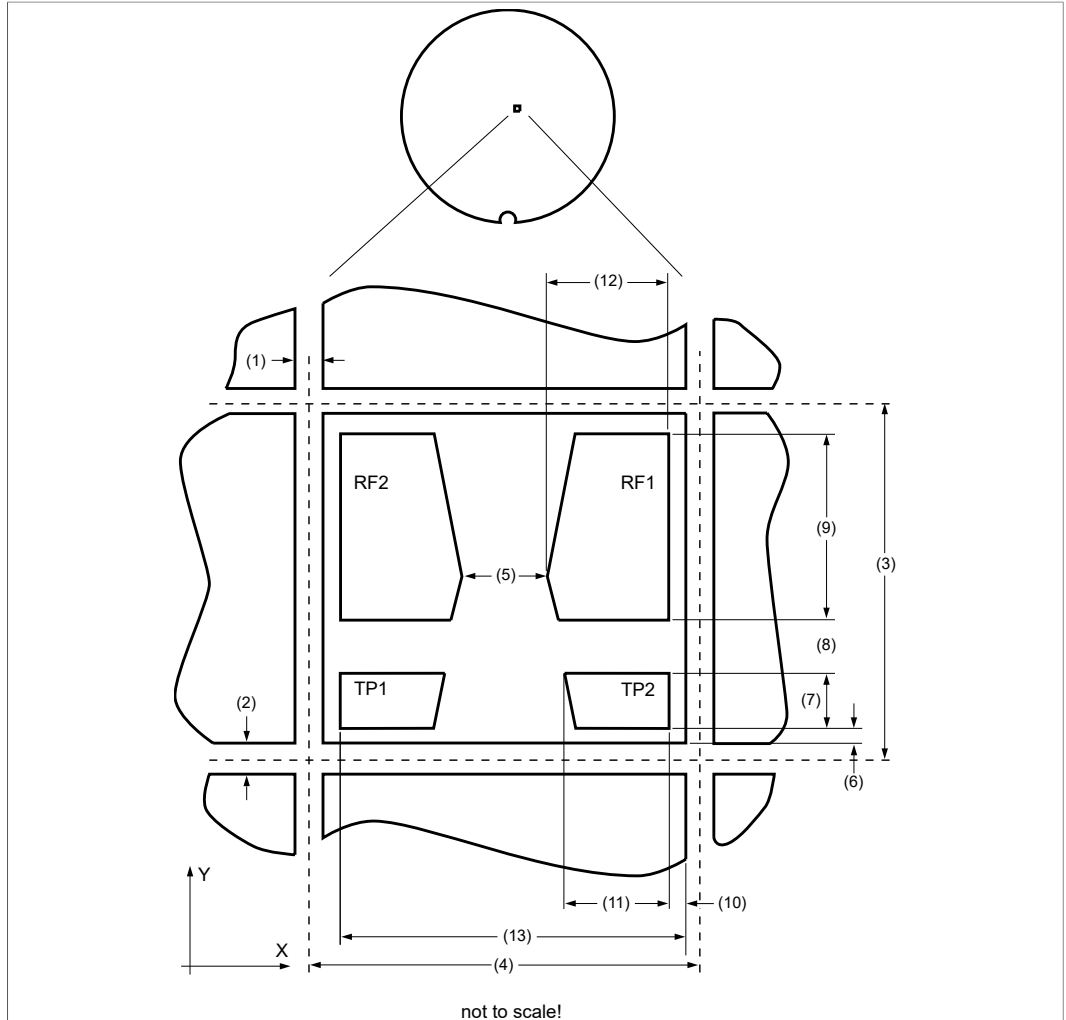


6.1 Pin description

Table 2. Pin description bare die

Symbol	Description
TP1	test pad 1
RF1	antenna connector 1
TP2	test pad 2
RF2	antenna connector 2

7 Wafer layout



aaa-038696

1. Die to Die distance (metal sealing - metal sealing) 39 μm , (X-scribe line width: 35 μm)
2. Die to Die distance (metal sealing - metal sealing) 39 μm , (Y-scribe line width: 35 μm)
3. Chip step, Y-length: 415 μm
4. Chip step, X-length: 465 μm
5. Bump to bump distance X (RF1 - RF2): 115 μm
6. Distance bump to metal sealing Y: 21.5 μm
7. Bump size (TP1, TP2) Y: 59.5 μm
8. Bump to bump distance Y (RF1 - TP2, RF2 - TP1): 50 μm
9. Bump size (RF1, RF2) Y: 223.5 μm
10. Distance bump to metal sealing X: 21.5 μm
11. Bump size (TP1, TP2) X: 114.5 μm
12. Bump size (RF1, RF2) X: 134 μm
13. Distance bump to metal sealing Y: 404.5 μm

Remark: TP1 and TP2 are electrically disconnected after dicing

Figure 3. UCODE 9, 12" wafer layout

8 Mechanical specification

UCODE 9 wafers are available in 120 µm thickness. The 120 µm thick wafer includes a 10 µm Polyimide spacer resulting in less coupling between the antenna and the active circuit, leaving more room for process control (for example, pressure).

8.1 Wafer specification

8.1.1 12 inch Wafer

See ["Data sheet - Delivery type description – General specification for 12" wafer on UV-tape with electronic fail die marking, BU-S&C document number: 1862**"](#)

Table 3. 12 inch specification

Wafer	
Designation	each wafer is scribed with batch number and wafer number
Diameter	300 mm (12") unsawn
Thickness	120 µm ± 15 µm
Number of pads	4
Pad location	non-diagonal / placed in chip corners
Process	CMOS 0.14 µm
Batch size	25 wafers
Net printed dies per wafer	343073
Wafer backside	
Material	Si
Treatment	ground and stress release
Roughness	R _a max. 0.5 µm, R _t max. 5 µm
Chip dimensions	
Die size excluding scribe	0.43 mm × 0.38 mm = 0.16 mm ²
Scribe line width:	x-dimension = 35 µm
	y-dimension = 35 µm
Passivation on front	
Type	Sandwich structure
Material	PE-Nitride (on top)
Thickness	1.75 µm total thickness of passivation
Polyimide spacer	10 µm ± 2 µm
Au pads	
Pad material	> 99.9 % pure Au
Pad hardness	35 – 80 HV 0.005
Pad shear strength	> 70 MPa
Pad height	3 µm

Table 3. 12 inch specification...continued

Pad height uniformity	
– within a die	max. 2 μm
– within a wafer	max. 4 μm
Pad flatness	max. 3 μm
Pad size	
– RF1, RF2 (max. details see wafer layout)	134 μm \times 223.5 μm
– TP1, TP2 (max. details see wafer layout)	114.5 μm \times 59.5 μm
Pad size variation	\pm 5 μm

8.1.2 Fail die identification

No ink dots are applied to the wafer.

Electronic wafer mapping (SECS II format) covers the electrical test results and additionally the results of mechanical/visual inspection.

See ["Data sheet - Delivery type description – General specification for 12" wafer on UV-tape with electronic fail die marking, BU-S&C document number: 1862**"](#)

8.1.3 Map file distribution

See ["Data sheet - Delivery type description – General specification for 12" wafer on UV-tape with electronic fail die marking, BU-S&C document number: 1862**"](#)

9 Functional description

9.1 Air interface standards

The UCODE 9 fully supports all parts of the "EPC™ Radio-Frequency Identity Protocols Generation-2 UHF RFID, Specification for RFID Air Interface, Protocol for Communications at 860 MHz to 960 MHz, Version 2.1".

9.2 Power transfer

The interrogator provides an RF field that powers the tag, equipped with a UCODE 9. The antenna transforms the impedance of free space to the chip input impedance in order to get the maximum power for the UCODE 9 on the tag.

The RF field, which is oscillating on the operating frequency provided by the interrogator, is rectified to provide a smoothed DC voltage to the analog and digital modules of the IC.

The antenna that is attached to the chip may use a DC connection between the two antenna pads. Therefore the UCODE 9 also enables loop antenna design.

9.3 Data transfer

9.3.1 Interrogator to tag Link

An interrogator transmits information to the UCODE 9 by modulating an UHF RF signal. The UCODE 9 receives both information and operating energy from this RF signal. Tags are passive, meaning that they receive all of their operating energy from the interrogator's RF waveform.

An interrogator is using a fixed modulation and data rate for the duration of at least one inventory round. It communicates to the UCODE 9 by modulating an RF carrier.

For further details, refer to ["Interrogator-to-tag \(R=>T\) communications"](#)

9.3.2 Tag to interrogator Link

Upon transmitting a valid command, an interrogator receives information from a UCODE 9 tag by transmitting an unmodulated RF carrier and listening for a backscattered reply. The UCODE 9 backscatters by switching the reflection coefficient of its antenna between two states in accordance with the data being sent. For further details, refer to ["Tag-to-Interrogator \(T=>R\) communications"](#)

The UCODE 9 communicates information by backscatter-modulating the amplitude and/or phase of the RF carrier. Interrogators shall be capable of demodulating either demodulation type.

The encoding format, selected in response to interrogator commands, is either FM0 baseband or Miller-modulated subcarrier.

9.4 Supported commands

UCODE 9 supports all **mandatory** EPCglobal v2.1 commands including

- KILL command

In addition, the UCODE 9 supports the following **optional** commands:

- Block Write (32 bit)

9.5 UCODE 9 memory

The UCODE 9 memory is implemented according to EPCglobal v2.1:

Table 4. UCODE 9 memory sections

Name	Size	Bank
Reserved memory (32 bit Kill password)	32 bit	00b
EPC (excluding 16 bit CRC-16 and 16-bit PC)	96 bit	01b
UCODE 9 Configuration Word	16 bit	01b
TID (including permalocked unique 48-bit serial number)	96 bit	10b

The logical address of all memory banks begins at zero (00h).

In addition to the four memory banks, one configuration word to handle the UCODE 9 specific features is available at EPC bank 01 address bit-200h. The configuration word is described in detail in [Section 9.6.1](#)

The TID complies to the GS1 EPC Tag Data Standard. See "[EPC Tag Data Standard, Release 1.10](#)"

9.5.1 UCODE 9 overall memory map

Table 5. UCODE 9 overall memory map

Bank	Address	Type	Content	Initial	Remark
Bank 00	00h to 1Fh	reserved	Kill password	all 00h	unlocked memory
	20h to 3Fh	reserved	Access password	all 00h	hardwired to 0, locked memory
Bank 01 EPC	00h to 0Fh	EPC	CRC-16: refer to " EPC Global Gen2v2.1 "		memory mapped calculated CRC
	10h to 14h	EPC	EPC length	00110b	unlocked memory
	15h	EPC	UMI	0b	hardwired to 0
	16h	EPC	XPC indicator	0b	hardwired to 0
	17h to 1Fh	EPC	numbering system indicator	00h	unlocked memory
	20h to 7Fh	EPC	EPC	[1]	unlocked memory
Bank 01 Config Word	200h	EPC	RFU	0b	locked memory
	201h	EPC	RFU	0b	locked memory
	202h	EPC	EPC NOK	0b	indicator bit
	203h	EPC	RFU	0b	locked memory
	204h	EPC	RFU	0b	locked memory
	205h	EPC	RFU	0b	locked memory
	206h	EPC	RFU	0b	locked memory
	207h	EPC	Self-Adjust disable	0b	permanent bit ^[2]
	208h	EPC	Dynamic backscatter	0b	permanent bit ^[2]
	209h	EPC	max. backscatter strength	1b	permanent bit ^[2]
	20Ah	EPC	RFU	0b	locked memory
	20Bh	EPC	RFU	0b	locked memory
	20Ch	EPC	RFU	0b	locked memory
	20Dh	EPC	RFU	0b	locked memory
	20Eh	EPC	RFU	0b	locked memory
20Fh	EPC	RFU	0b	locked memory	
Bank 10 TID	00h to 07h	TID	allocation class identifier	1110 0010b	locked memory
	08h to 13h	TID	tag mask designer identifier	1000 0000 0110b	locked memory
	14h	TID	config word indicator	1b ^[3]	locked memory
	15h to 1Fh	TID	tag model number	TMNR ^[4]	locked memory
	20h to 2Fh	TID	XTID header	2000h	locked memory
	30h to 5Fh	TID	serial number	SNR	locked memory

[1] HEX E280 6995 0000 nnnn nnnn nnnn 0000 0000 where n are the nibbles of the SNR from the TID

[2] Permanent bit: permanently stored bits in the memory; Read/Writeable according to EPC bank lock status, see [Section 9.6.1](#)

[3] Indicates the existence of a Configuration Word at the end of the EPC number

[4] See [Figure 4](#)

9.5.2 UCODE 9 TID memory details

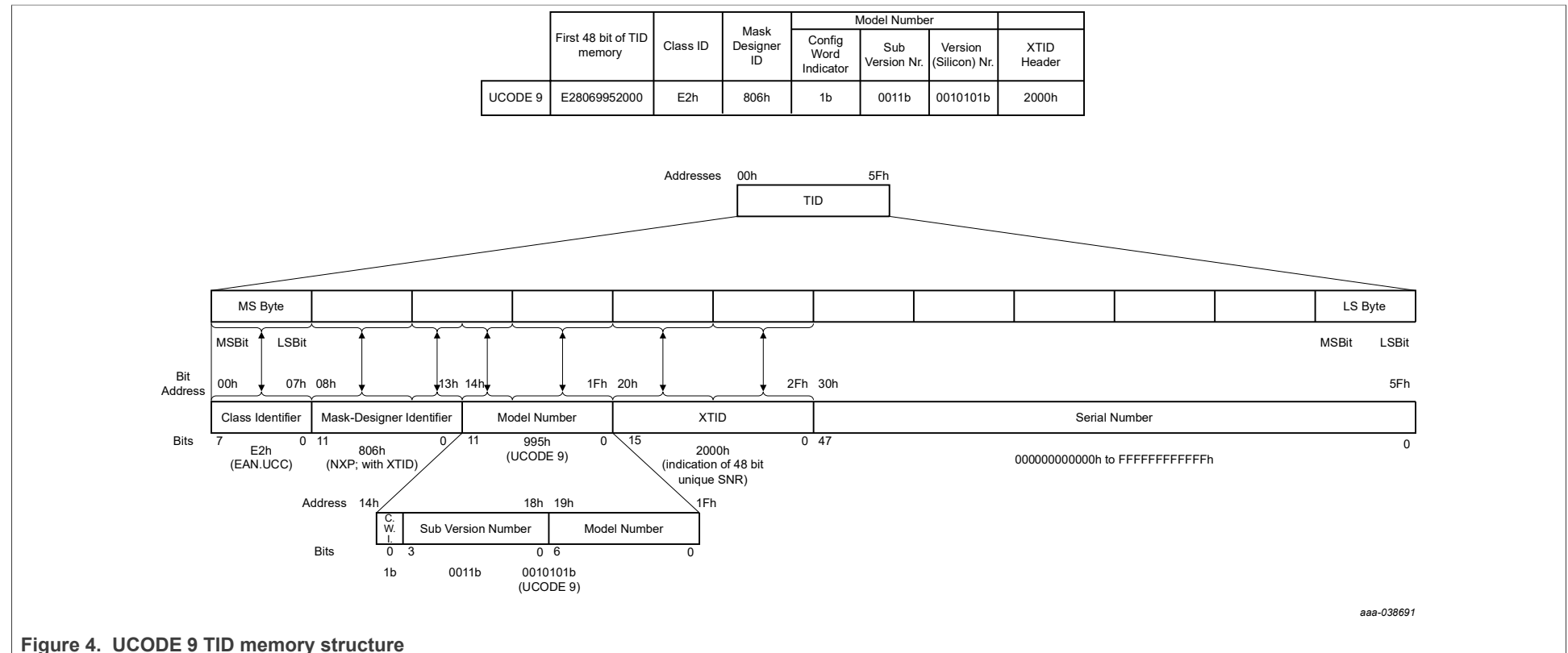


Figure 4. UCODE 9 TID memory structure

9.6 Supported features

The UCODE 9 is equipped with a number of additional features. They are implemented in such a way that standard EPCglobal READ / WRITE / SELECT commands can be used to operate these features.

The Configuration Word, as mentioned in the memory map, describes the additional features at address 200h of the EPC memory.

Bit 14h of the TID indicates the existence of a Configuration Word. This flag enables the selection of configuration word enhanced transponders in mixed tag populations.

9.6.1 UCODE 9 features control mechanism

The different features of the UCODE 9 can be activated / de-activated by addressing or changing the content of the corresponding bit in the configuration word at address 200h in the EPC memory bank (see [Table 6](#)). The de-activation of the action bit features will only happen after chip reset.

Table 6. Configuration word UCODE 9

Indicator bit			Locked memory				Permanent bit
RFU	RFU	EPC NOK	RFU	RFU	RFU	RFU	Self-Adjust disable
0	1	2	3	4	5	6	7

Table 7. Configuration word UCODE 9 ... continued

Permanent bit	Permanent bit	Locked memory					
Dynamic backscatter	max.backscatter strength	RFU	RFU	RFU	RFU	RFU	RFU
8	9	10	11	12	13	14	15

The configuration word contains 3 different type of bits:

- **Permanent bits:** permanently stored bits in the memory
 Self-Adjust disable
 Dynamic backscatter
 Max. Backscatter Strength
- **Indicator bit:** cannot be changed by command
 EPC NOK

The activation or the de-activation of the feature behind the permanent bits happens only when attempting to write a "1" value to the related bit (value toggling) - writing "0" value has no effect. If the feature is activated, the related bit will be read with a "1" value and, if de-activated, with a "0" value. The permanent bits can only be toggled by using standard EPC WRITE (not a BlockWrite) if the EPC bank is unlocked. If the EPC is permalocked, they cannot be changed.

9.6.2 Self-Adjust

9.6.2.1 Description

The UCODE 9 has an automatic mechanism implemented which adjusts the chip sensitivity to a maximum in the operated environment. This adjustment will be performed at startup and selects between three different input capacitance values (center capacitance -60 fF / +100 fF). The feature is enabled by default, but can also be deactivated by the config word bit 207h (Self-Adjust disable). In case of deactivation, the center capacitance is used.

9.6.3 Dynamic backscatter

9.6.3.1 Description

UCODE 9 introduces the new enhanced Dynamic backscatter feature in addition to the standard UCODE backscatter control. The three modes can be controlled by modifying bit 208h and bit 209h within the configuration word. Per default, maximum backscatter is enabled in order to achieve maximum read rates. In case backscatter strength reduction is necessary nominal backscatter strength can be selected.

The third new introduced Dynamic Backscatter mode enables maximum backscatter at low chip power levels and gradually reduces the backscatter strength at high-power levels enabling the best performance and also meet regulatory limits.

Table 8. Backscatter Control

Dynamic Backscatter Bit	Max. Backscatter Bit	
0	0	Nominal Backscatter
0	1	Maximum Backscatter
1	0	Dynamic Backscatter
1	1	Maximum Backscatter

9.6.4 Memory Safeguard

9.6.4.1 Description

The Memory Safeguard of UCODE 9 consist of two different countermeasures which ensure integrity of the stored data:

ECC (Error correction code):

The implemented ECC is applied on the complete UCODE 9 memory and requires no user action. With this feature, a single bit failure in the memory is detected and corrected automatically. In case of 2-bit fail, an indication as described below is given.

EPC Memory:

Config word bit 202h (EPC NOK) provides an indication that a 2-bit failure occurred in the EPC memory by changing its value to "1". In such a case, UCODE 9 will respond with an EPC value of F's indicating a corrupted EPC. A read of the EPC memory content will provide the actual content.

Parity check:

A parity check on the TID is implemented to offer the possibility to identify a change in the TID. The parity bit (Even parity) will be calculated and locked in the manufacturing process. For a check, the TID content needs to be read out and parity checked.

9.6.5 Pre-serialization of the 96-bit EPC

9.6.5.1 Description

UCODE 9 is delivered with a pre-serialized content of the 96-bit EPC, which is the initial programmed length of the EPC.

The EPC content is identical to the TID content except of the 16-bit XTID content which is set to 16-bit 0's.

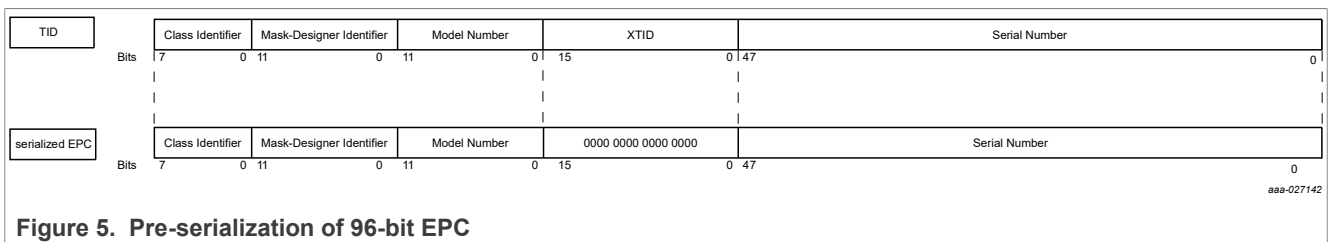


Figure 5. Pre-serialization of 96-bit EPC

9.6.6 Single-slit antenna solution

9.6.6.1 Description

In UCODE 9, the test pads TP1 and TP2 are electrically disconnected and therefore can be safely short-circuited to the RF pads (RF1, RF2) (see figure below).

Single-slit antenna enables easier assembly and antenna design. In addition to the standard antenna assembly, the related increased input capacitance (see [Table 10](#)) can be used for optimization for different antenna design.

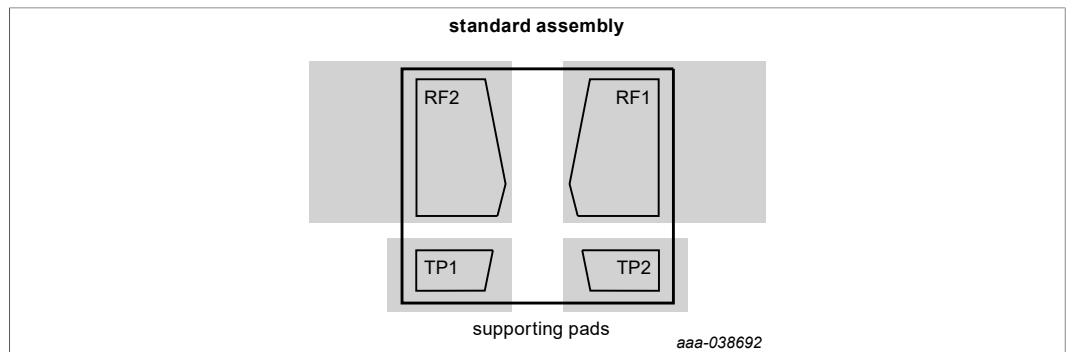


Figure 6. Standard antenna design versus single-slit antenna

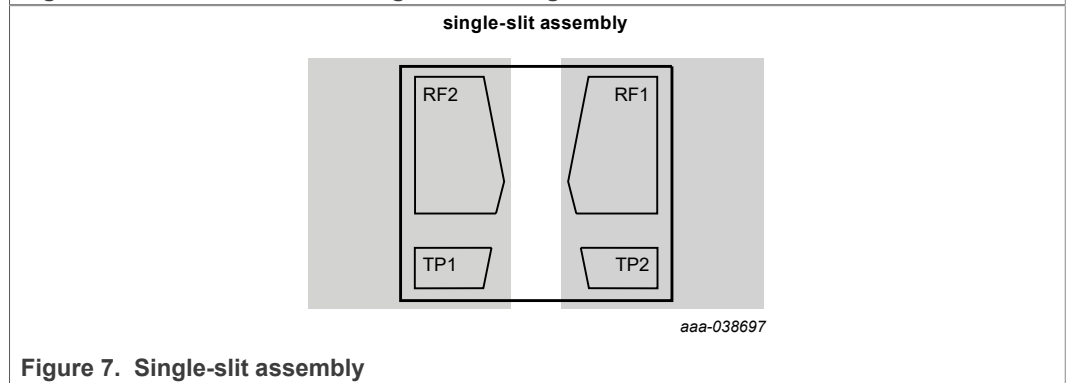


Figure 7. Single-slit assembly

9.6.7 Large Pads

9.6.7.1 Description

The large gold pads of UCODE 9 enable more robust and reliable assembly. This pad design allows not only more freedom in the placement accuracy (see [Figure 8](#)). It also brings advantages in high-speed assembly due to the dual axis glue spacer (see [Figure 9](#)).

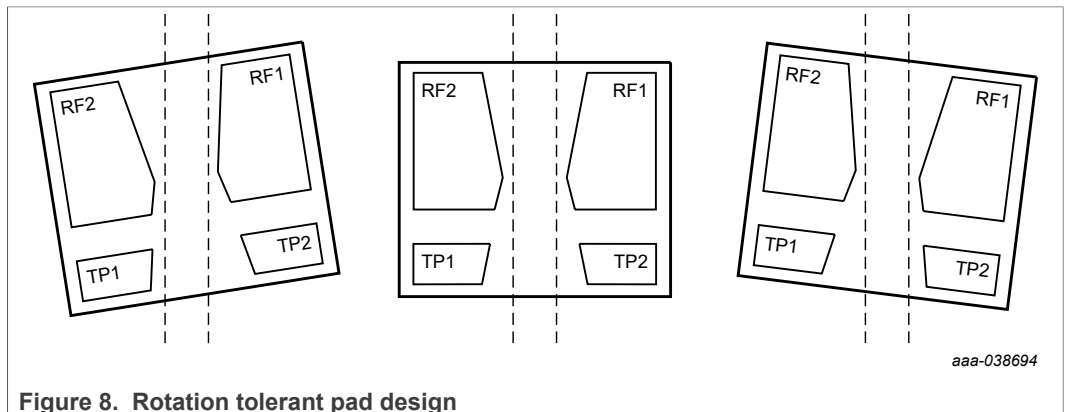


Figure 8. Rotation tolerant pad design

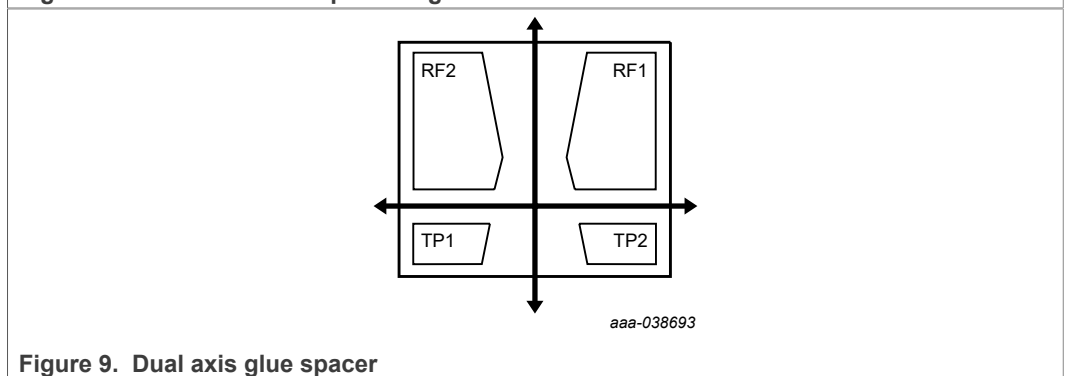


Figure 9. Dual axis glue spacer

9.6.8 Permalock

UCODE 9 permalock is implemented according to EPCglobal using the LOCK command with a payload of FFFFFh.

For any payload other than FFFFFh UCODE 9 backscatters an error code.

10 Limiting values

Table 9. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to RFN. ^{[1] [2]}

Symbol	Parameter	Conditions	Min	Max	Unit
Bare die limitations					
T _{stg}	storage temperature		-55	+125	°C
T _{amb}	ambient temperature		-40	+85	°C
V _{ESD}	electrostatic discharge voltage	human body model (HBM) ^[3]	-	± 2	kV
Pad limitations					
P _i	input power	maximum power dissipation, RF1/RF2 pad	-	100	mW

- [1] Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any conditions other than those described in the Operating Conditions and Electrical Characteristics section of this specification is not implied.
- [2] This product includes circuitry specifically designed for the protection of its internal devices from the damaging effects of excessive static charge. Nonetheless, it is suggested that conventional precautions be taken to avoid applying greater than the rated maxima.
- [3] According to ANSI/ESDA/JEDEC JS-001
- [4] For ESD measurement, the die chip has been mounted into a CDIP8 package.

CAUTION



This device is sensitive to ElectroStatic Discharge (ESD). Observe precautions for handling electrostatic sensitive devices. Such precautions are described in the *ANSI/ESD S20.20, IEC/ST 61340-5, JESD625-A* or equivalent standards.

11 Characteristics

11.1 UCODE 9 bare die characteristics

Table 10. UCODE 9 RF interface characteristics (RF1, RF2)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
f_i	input frequency		840	-	960	MHz
$P_{I(min)}$	minimum input power	READ sensitivity [1]	-	- 24	-	dBm
$P_{I(min)}$	minimum input power	WRITE sensitivity [1]	-	-22	-	dBm
t_{16bit}	encoding speed	16-bit [2]	-	0.6	-	ms
		32-bit (block write) [2]	-	1	-	ms
C_i	chip input capacitance	parallel [3] [4] [5]	-	0.715	-	pF
R_p	chip resistance	parallel [4]	-	3.6	-	k Ω
Z	chip impedance	915 MHz [3] [4] [5]	-	9-j243	-	Ω
Z	typical assembled impedance (see Figure 6)	915 MHz [6] [7] [5]	-	15-j231	-	Ω
Z	typical assembled impedance in case of single-slit antenna assembly (see Figure 7)	915 MHz [6] [8] [5]	-	10-j191	-	Ω

- [1] Tag sensitivity on a 2.15 dBi gain antenna
- [2] When the memory content is "0000...".
- [3] Measured with a 50 Ω source impedance directly on the chip
- [4] At minimum operating power
- [5] at center capacitor of Self-Adjust
- [6] The antenna shall be matched to this impedance
- [7] Assuming 35 fF additional assembly capacitance
- [8] Assuming 195 fF additional assembly+test pad capacitance

Table 11. Table 13. UCODE 9 memory characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
EEPROM characteristics						
t_{ret}	retention time	$T_{amb} \leq 55 \text{ }^\circ\text{C}$	20	-	-	year
$N_{endu(W)}$	write endurance		100k	-	-	cycle

12 Packing information

12.1 Wafer

See ["Data sheet - Delivery type description – General specification for 12" wafer on UV-tape with electronic fail die marking, BU-S&C document number: 1862**"](#)

13 Abbreviations

Table 12. Abbreviations

Acronym	Description
CRC	Cyclic Redundancy Check
CW	Continuous Wave
DSB-ASK	Double Side Band-Amplitude Shift Keying
DC	Direct Current
EAS	Electronic Article Surveillance
EEPROM	Electrically Erasable Programmable Read Only Memory
EPC	Electronic Product Code (containing Header, Domain Manager, Object Class and Serial Number)
FM0	Bi phase space modulation
G2	Generation 2
IC	Integrated Circuit
PIE	Pulse Interval Encoding
PSF	Product Status Flag
RF	Radio Frequency
UHF	Ultra High Frequency
SECS	Semi Equipment Communication Standard
TID	Tag IDentifier

14 References

1. EPCglobal: EPC Radio-Frequency Identity Protocols Class-1 Generation-2 UHF RFID Protocol for Communications at 860 MHz – 960 MHz, Version 2.1 (July 2018)
2. EPCglobal: EPC Tag Data Standard, Release 1.13 (November 2019)
3. Data sheet - Delivery type description – General specification for 12" wafer on UV-tape with electronic fail die marking, BU-S&C document number: 1862**¹

¹ ** ... document version number

15 Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Supersedes
SL3S1206 v.3.0	20201215	Product data sheet	530920
Modifications:	<ul style="list-style-type: none"> Data sheet status changed into "Product data sheet", no content change 		
530920	20201203	Preliminary data sheet	530911
Modifications:	<ul style="list-style-type: none"> Section 7 "Wafer layout": Update of pad dimensions Section 9.5.2 "UCODE 9 TID memory details": Update of TMN Section 9.6.2 "Self-Adjust": Capacitance values added Section 11.1 "UCODE 9 bare die characteristics": Update 		
530911	20200820	Objective data sheet	530910
Modifications:	<ul style="list-style-type: none"> Section 10 "Limiting values": T_{amb} updated Section 9.6.3 "Dynamic backscatter": Paragraph format updated Section 9.6.4 "Memory Safeguard": Paragraph added Section 2.1 "Key features": Memory safeguard added 		
530910	20200722	Objective data sheet	-

16 Legal information

16.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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Tables

Tab. 1.	Ordering information	4	Tab. 8.	Backscatter Control	15
Tab. 2.	Pin description bare die	6	Tab. 9.	Limiting values	19
Tab. 3.	12 inch specification	8	Tab. 10.	UCODE 9 RF interface characteristics (RF1, RF2)	20
Tab. 4.	UCODE 9 memory sections	11	Tab. 11.	Table 13. UCODE 9 memory characteristics	20
Tab. 5.	UCODE 9 overall memory map	12	Tab. 12.	Abbreviations	22
Tab. 6.	Configuration word UCODE 9	14	Tab. 13.	Revision history	24
Tab. 7.	Configuration word UCODE 9 ... continued	14			

Figures

Fig. 1.	Block diagram of UCODE 9 IC	5	Fig. 6.	Standard antenna design versus single-slit antenna	17
Fig. 2.	Pinning bare die	6	Fig. 7.	Single-slit assembly	17
Fig. 3.	UCODE 9, 12" wafer layout	7	Fig. 8.	Rotation tolerant pad design	18
Fig. 4.	UCODE 9 TID memory structure	13	Fig. 9.	Dual axis glue spacer	18
Fig. 5.	Pre-serialization of 96-bit EPC	16			

Contents

1 General description 1

2 Features and benefits2

2.1 Key features 2

2.1.1 Memory2

2.2 Supported features 2

3 Applications3

3.1 Target market3

3.2 Applications3

4 Ordering information 4

5 Block diagram 5

6 Pinning information 6

6.1 Pin description 6

7 Wafer layout7

8 Mechanical specification8

8.1 Wafer specification 8

8.1.1 12 inch Wafer 8

8.1.2 Fail die identification9

8.1.3 Map file distribution 9

9 Functional description10

9.1 Air interface standards10

9.2 Power transfer 10

9.3 Data transfer 10

9.3.1 Interrogator to tag Link 10

9.3.2 Tag to interrogator Link10

9.4 Supported commands11

9.5 UCODE 9 memory 11

9.5.1 UCODE 9 overall memory map 12

9.5.2 UCODE 9 TID memory details 13

9.6 Supported features 14

9.6.1 UCODE 9 features control mechanism 14

9.6.2 Self-Adjust 15

9.6.2.1 Description 15

9.6.3 Dynamic backscatter 15

9.6.3.1 Description 15

9.6.4 Memory Safeguard 15

9.6.4.1 Description 15

9.6.5 Pre-serialization of the 96-bit EPC 16

9.6.5.1 Description 16

9.6.6 Single-slit antenna solution 17

9.6.6.1 Description 17

9.6.7 Large Pads 18

9.6.7.1 Description 18

9.6.8 Permalock 18

10 Limiting values 19

11 Characteristics 20

11.1 UCODE 9 bare die characteristics 20

12 Packing information21

12.1 Wafer 21

13 Abbreviations 22

14 References 23

15 Revision history 24

16 Legal information 25

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